ON Semiconductor®



	Change wire size of U	Change wire size of Ultrafast DPAK package (620 device series) from 5 mils to 8 mils			
Proposed First Ship date:	31 Dec 2021 or earlie	31 Dec 2021 or earlier if approved by customer			
Contact Information:	Contact your local ON	Contact your local ON Semiconductor Sales Office or Danh.Trinh@onsemi.com			
PCN Samples Contact:	Sample requests are t Initial PCN or Final PC Samples delivery timi	Contact your local ON Semiconductor Sales Office or < <u>PCN.samples@onsemi.com</u> >. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.			
Type of Notification:	advance notification a change details and de plan.The completed o Product/Process Char Product/Process Char	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < <u>PCN.Support@onsemi.com</u> >			
Marking of Parts/ Traceability of Change:	Clean date code will k	Clean date code will be advised upon of request.			
Change Category:	Assembly Change	Assembly Change			
Change Sub-Category(s):	Material Change	Material Change			
Sites Affected:					
ON Semiconductor Sites		External Foundry/Subcon Sites			
ON Semiconductor Seremban, Malaysia		NANTONG Tong Fu MICROELECTRONICS CO.,LTD.			
ON Semiconductor Vietnam					
Description and Durnsson					
Description and Purpose:					
Description and Purpose: This IPCN announces the plan to qual robustness, with proven superior prod Once completing of qualification and a	uct performance.		n DPAK package. This change is to improve qualit be changed with new Bill of Material.		
This IPCN announces the plan to qual robustness, with proven superior prod	uct performance.	ll products listed here will			



Qualification Plan:

QV DEVICE NAME: MURD620CTT4G (Mesa Ultrafast) PACKAGE: DPAK

Test	Specification	Condition	Interval
HTSL	JESD22-A103	Ta = 175 °C	1008 hrs
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta = +25°C, deltaTj = 100°C max, Ton = Toff = 2min	15000 cyc
TC	JESD22-A104	Ta = -65°C to +150°C	1000 cyc
UHAST	JESD22-A102	130°C, 100% RH, 18.8psig, unbiased	96 hrs
H3TRB	JESD22-A101	85°C, 85% RH, bias = 100V max	1008 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
RSH	JESD22- B106	Ta = 265°C, 10 sec	
SD	JSTD002	Ta = 245°C, 10 sec	

Estimated date for qualification completion: 30 November 2021

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle	
MSRD620CTT4G	MURD620CTT4G	
MSRD620CTG	MURD620CTT4G	
MURD620CTT4G	MURD620CTT4G	
MURD620CTG	MURD620CTT4G	

Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
MSRD620CTT4G		MURD620CTT4G		
MURD620CTT4G		MURD620CTT4G		
MURD620CTG		MURD620CTT4G		
MSRD620CTG		MURD620CTT4G		